



IFW 1765
[10191/3964]

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Franz LAERMER et al.
Serial No. : 10/530,612
Filed : December 30, 2005
For : **PLASMA SYSTEM AND METHOD FOR
ANISOTROPICALLY ETCHING STRUCTURES
INTO A SUBSTRATE**

Art Unit : 1765
Examiner : Maki A. Angadi
Confirmation No. : 6739

Mail Stop: Amendment
Commissioner for Patents
P.O. Box 1450
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I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Mail Stop: Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on

Date: Jan. 11, 2007 Reg. No. 35,952

Signature: [Signature]

Gerard A. Messina

AMENDMENT

SIR:

In response to an October 11, 2006 Office Action in the above-identified application, please amend, without prejudice, the above-captioned application as follows.

Amendments to the Claims are reflected in the **Listing of Claims**, which begins on page 2 of this paper.

Remarks begin on page 7 of this paper.